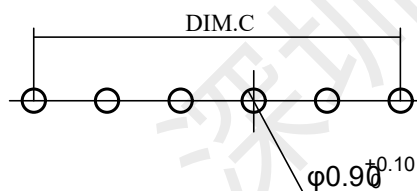
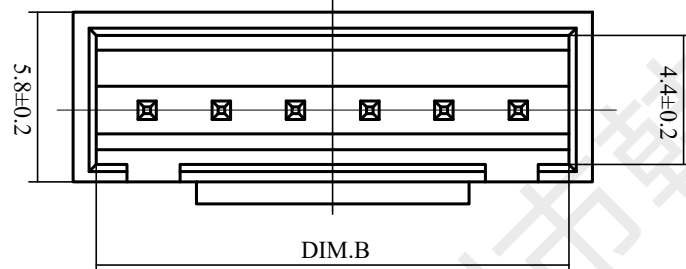
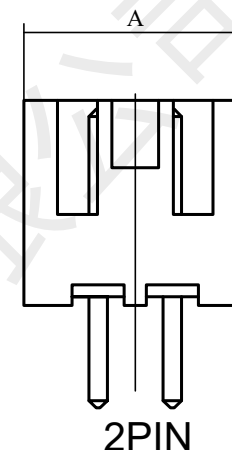
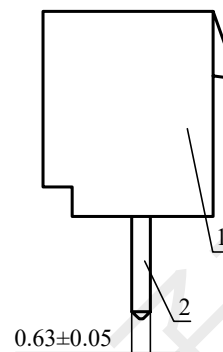
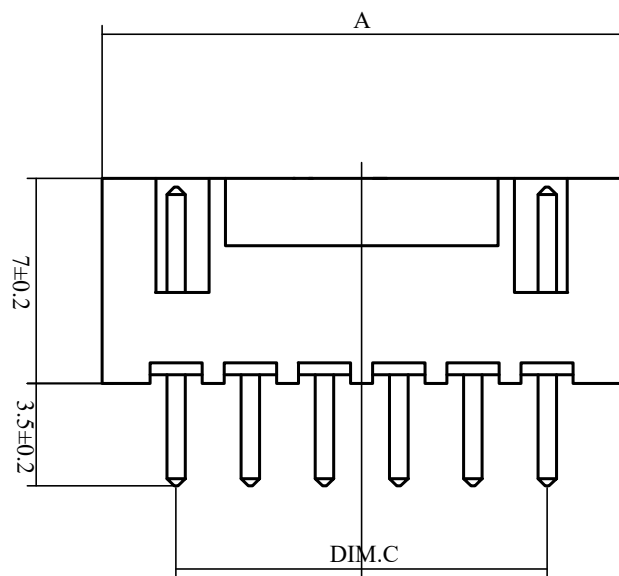


REV.	EC#	DESCRIPTION	DATE DRAWN	CHECK	APPROVED
1.00		初版发行	2020-8-28		

15P	40	38.6	35
14P	37.5	36.1	32.5
13P	35	33.6	30
12P	32.5	31.1	27.5
11P	30	28.6	25
10P	27.5	26.1	22.5
9P	25	23.6	20
8P	22.5	21.1	17.5
7P	20	18.6	15
6P	17.5	16.1	12.5
5P	15	13.6	10
4P	12.5	11.1	7.5
3P	10	8.6	5
2P	7.5	6.1	2.5
NUMBER OF PINS	DIM.A	DIM.B	DIM.C



PCB LAYOUT

技术要求:

- 1) 材质: 见附表;
- 2) 电镀: 见附表;
- 3) 塑件表面平整、光洁、无毛刺、气泡、烧焦、变形、浇口无拉伤、多料或缺料等不良现象;
- 4) 端子表面无氧化、电镀不良等现象。

适应基板厚度：1.2mm~1.6mm

温度范围: -25℃~85℃

额定电压: 250V AC/DC

额定电流: 3A

接触电阻: $\leq 0.01\Omega$

绝缘电阻: $\geq 1000\text{M}\Omega$

耐 压: 1000V AC/minute

2	PIN	n PCS	材质:黄铜,电镀:镀亮锡60u"MIN	
1	Housing	1 PCS	材质:PA66 (UL94V-0),颜色:本色	
NO.	NAME	Q'TY	DESCRIPTION	
 深圳市韩下电子有限公司				
DRAW :	黄彬	2020-8-28	TITLE:	
DESIGN:			HX-XHB2.54-3PZZ	
CHECK:	张伟	2020-8-28	SERIES: 1501 SERIES	
APPROVED	罗小春	2020-8-28	P/N:	
CUSTOMER DRAWING			REV. 1.00	SCALE N/A
			UNIT:	SHEET:
			mm	1/1
				